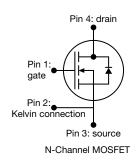
Vishay Siliconix

E Series Power MOSFET





PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.070			
Q _g max. (nC)	6	3			
Q _{gs} (nC)	1	9			
Q _{gd} (nC)	10				
Configuration	Sin	Single			

FEATURES

- 4th generation E series technology
- Low figure of merit (FOM) R_{on} x Q_g
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and halogen-free	SIHH080N60E-T1-GE3

ABSOLUTE MAXIMUM RATINGS	(T _C = 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	600	V	
Gate-source voltage			V_{GS}	± 30	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Continuous drain current (T _{.I} = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		32	A	
Continuous drain current (1) = 150°C)	VGS at 10 V	T _C = 100 °C	Ι _D	20		
Pulsed drain current ^a			I _{DM}	96		
Linear derating factor				1.47	W/°C	
Single pulse avalanche energy ^b			E _{AS}	226	mJ	
Maximum power dissipation			P_{D}	184	W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$			dv/dt	100	V/ns	
Reverse diode dv/dt ^d				10	V/IIS	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4.0 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting T_J = 25 °C



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER SYMBOL TYP. MAX. UNIT					
Maximum junction-to-ambient	R_{thJA}	39	51	°C/W	
Maximum junction-to-case (drain)	R_{thJC}	0.51	0.68	C/ VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} =	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.64	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	3.0	-	5.0	V
Outros and halous	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage		,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zoro goto voltago droin ourrent	1	V _{DS} =	600 V, V _{GS} = 0 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 17 A	-	0.070	0.080	Ω
Forward transconductance ^a	9 _{fs}	V _{DS}	= 20 V, I _D = 17 A	-	4.6	-	S
Dynamic							
Input capacitance	C _{iss}		V _{GS} = 0 V,	-	2557	-	
Output capacitance	C _{oss}	Ţ,	$V_{DS} = 100 \text{ V},$	-	105	-	1
Reverse transfer capacitance	C _{rss}		f = 1 MHz		6	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	79	-	pF
Effective output capacitance, time related ^b	C _{o(tr)}			-	499	-	
Total gate charge	Qg		V _{GS} = 10 V		42	63	
Gate-source charge	Q _{gs}	V _{GS} = 10 V			19	-	nC
Gate-drain charge	Q _{gd}	1		-	10	-	
Turn-on delay time	t _{d(on)}			-	31	62	
Rise time	t _r	V _{DD} = 480 V, I _D = 17 A,		-	96	144	
Turn-off delay time	t _{d(off)}	V _{GS} =	$=$ 10 V, R _g = 9.1 Ω	-	37	74	ns
Fall time	t _f		1		31	62	
Gate input resistance	R_g	f = 1 MHz		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	es						
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	35	
Pulsed diode forward current	I _{SM}			-	-	96	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 17 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	10 20 0,10 11 1,100 - 0 0		-	441	882	ns
Reverse recovery charge	Q _{rr}		$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 17 \text{A},$		5.2	10.4	μC
Reverse recovery current	I _{RRM}	di/dt = 80 A/ μ s, V _R = 25 V		_	21	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

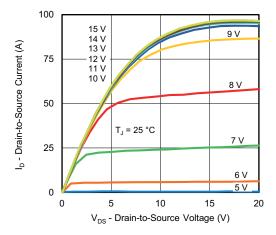


Fig. 1 - Typical Output Characteristics

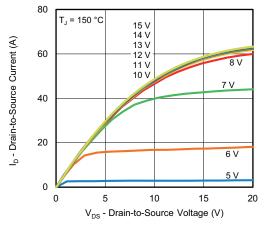


Fig. 2 - Typical Output Characteristics

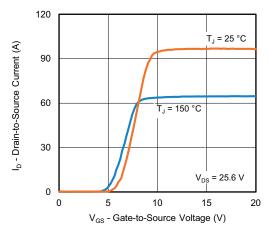


Fig. 3 - Typical Transfer Characteristics

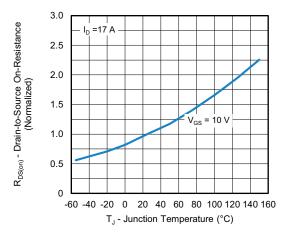


Fig. 4 - Normalized On-Resistance vs. Temperature

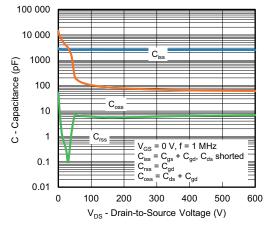


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

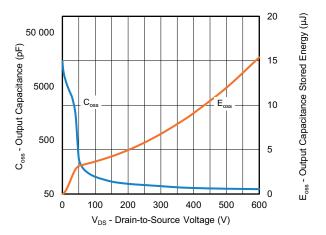


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



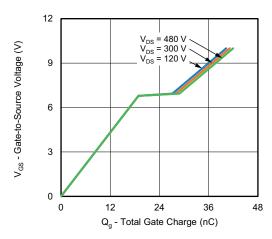


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

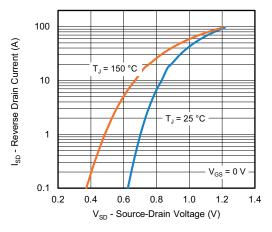


Fig. 8 - Typical Source-Drain Diode Forward Voltage

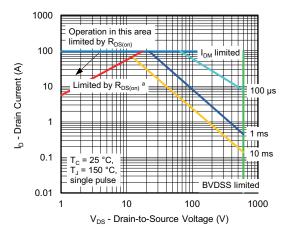


Fig. 9 - Maximum Safe Operating Area



a. $V_{GS} > minimum \ V_{GS}$ at which $R_{DS(on)}$ is specified

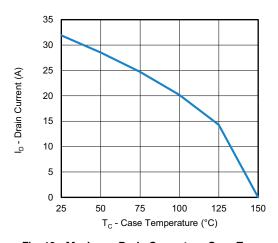


Fig. 10 - Maximum Drain Current vs. Case Temperature

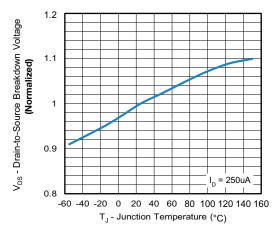


Fig. 11 - Temperature vs. Drain-to-Source Voltage



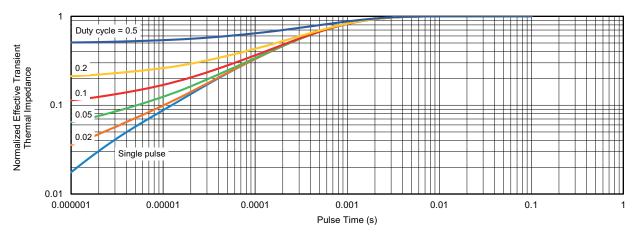


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

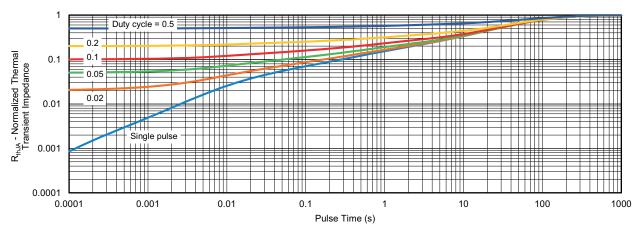


Fig. 13 - Normalized Transient Thermal Impedance, Junction-to-Ambient

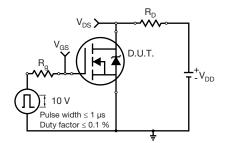


Fig. 14 - Switching Time Test Circuit

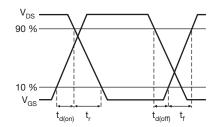


Fig. 15 - Switching Time Waveforms



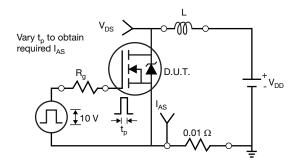


Fig. 16 - Unclamped Inductive Test Circuit

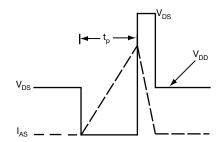


Fig. 17 - Unclamped Inductive Waveforms

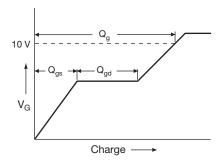


Fig. 18 - Basic Gate Charge Waveform

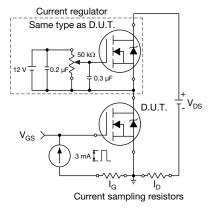
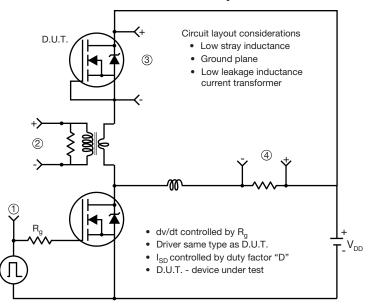


Fig. 19 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



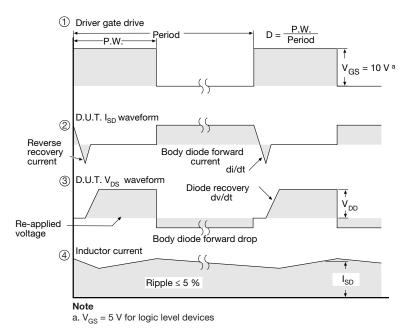


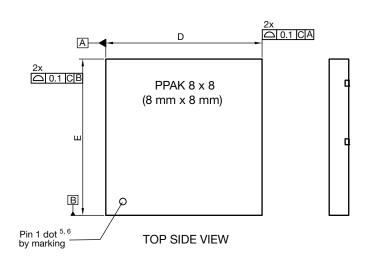
Fig. 20 - For N-Channel

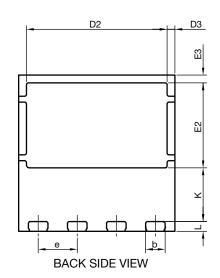
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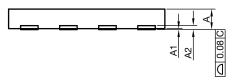


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PowerPAK® 8 x 8 Case Outline







DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2		020 ref.			0.008 ref.		
b	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3	0.40 BSC			0.016 BSC			
е		2.00 BSC		0.079 BSC			
Е	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3	0.40 BSC			0.016 BSC			
K	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N ⁽³⁾	8				8		

Notes

- (1) Use millimeters as the primary measurement
- (2) Dimensioning and tolerances conform to ASME Y14.5 M 1994
- (3) N is the number of terminals
- (4) The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
- (5) Exact shape and size of this feature is optional

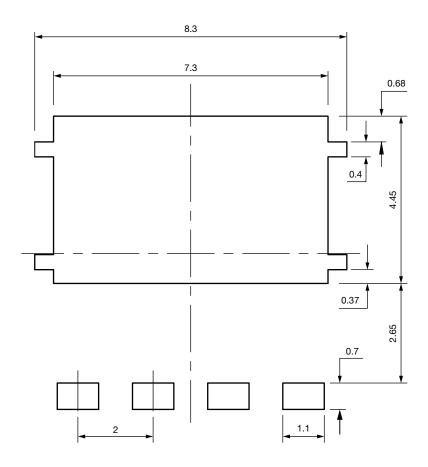
ECN: E20-0518-Rev. B, 28-Sep-2020

DWG: 6041

Revision: 28-Sep-2020 1 Document Number: 67859



Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



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